

## GENERAL DESCRIPTION

Glass passivated thyristors in a plastic envelope, intended for use in applications requiring high bidirectional blocking voltage capability and high thermal cycling performance. Typical applications include motor control, industrial and domestic lighting, heating and static switching.

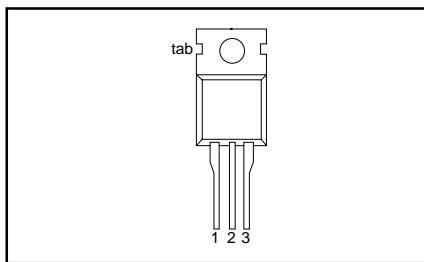
## QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX. BT145- 500R 500	MAX. 600R 600	MAX. 800R 800	UNIT V
$V_{DRM}$ , $V_{RRM}$	Repetitive peak off-state voltages				
$I_{T(AV)}$	Average on-state current	16	16	16	A
$I_{T(RMS)}$	RMS on-state current	25	25	25	A
$I_{TSM}$	Non-repetitive peak on-state current	300	300	300	A

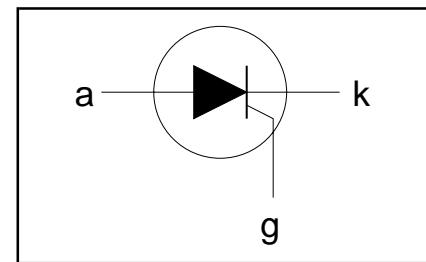
## PINNING - TO220AB

PIN	DESCRIPTION
1	cathode
2	anode
3	gate
tab	anode

## PIN CONFIGURATION



## SYMBOL



## LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.			UNIT
$V_{DRM}$ , $V_{RRM}$	Repetitive peak off-state voltages		-	-500R 500 <sup>1</sup>	-600R 600 <sup>1</sup>	-800R 800	V
$I_{T(AV)}$	Average on-state current	half sine wave; $T_{mb} \leq 101^\circ\text{C}$	-	16			A
$I_{T(RMS)}$	RMS on-state current	all conduction angles	-	25			A
$I_{TSM}$	Non-repetitive peak on-state current	half sine wave; $T_j = 25^\circ\text{C}$ prior to surge					
$I^2t$	$I^2t$ for fusing	$t = 10\text{ ms}$	-	300			A
$dI_T/dt$	Repetitive rate of rise of on-state current after triggering	$t = 8.3\text{ ms}$	-	330			A
$I_{GM}$	$I^2t$ for fusing	$t = 10\text{ ms}$	-	450			A <sup>2</sup> s
$V_{GM}$	Peak gate current	$I_{TM} = 50\text{ A}; I_G = 0.2\text{ A};$	-	200			A/ $\mu\text{s}$
$V_{RGM}$	Peak gate voltage	$dI_G/dt = 0.2\text{ A}/\mu\text{s}$					
$P_{GM}$	Peak reverse gate voltage		-	5			V
$P_{G(AV)}$	Peak gate power		-	5			V
$T_{stg}$	Average gate power		-	5			W
$T_j$	Storage temperature	over any 20 ms period	-	20			W
	Operating junction temperature		-40	0.5			
			-	150			°C
			-	125			°C

## THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th\ j\text{-}mb}$	Thermal resistance junction to mounting base		-	-	1.0	K/W
$R_{th\ j\text{-}a}$	Thermal resistance junction to ambient	in free air	-	60	-	K/W

## STATIC CHARACTERISTICS

$T_j = 25^\circ\text{C}$  unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$I_{GT}$	Gate trigger current	$V_D = 12\text{ V}; I_T = 0.1\text{ A}$	-	5	35	mA
$I_L$	Latching current	$V_D = 12\text{ V}; I_{GT} = 0.1\text{ A}$	-	25	80	mA
$I_H$	Holding current	$V_D = 12\text{ V}; I_{GT} = 0.1\text{ A}$	-	20	60	mA
$V_T$	On-state voltage	$I_T = 30\text{ A}$	-	1.1	1.5	V
$V_{GT}$	Gate trigger voltage	$V_D = 12\text{ V}; I_T = 0.1\text{ A}$ $V_D = V_{DRM(max)}; I_T = 0.1\text{ A}; T_j = 125^\circ\text{C}$	-	0.6	1.0	V
$I_D, I_R$	Off-state leakage current	$V_D = V_{DRM(max)}; V_R = V_{RRM(max)}; T_j = 125^\circ\text{C}$	0.25	0.4	-	V
			-	0.2	1.0	mA

## DYNAMIC CHARACTERISTICS

$T_j = 25^\circ\text{C}$  unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$dV_D/dt$	Critical rate of rise of off-state voltage	$V_{DM} = 67\% V_{DRM(max)}; T_j = 125^\circ\text{C};$ exponential waveform; gate open circuit	200	500	-	V/ $\mu$ s
$t_{gt}$	Gate controlled turn-on time	$I_{TM} = 40\text{ A}; V_D = V_{DRM(max)}; I_G = 0.1\text{ A};$ $dI_G/dt = 5\text{ A}/\mu\text{s}$	-	2	-	$\mu$ s
$t_q$	Circuit commutated turn-off time	$V_D = 67\% V_{DRM(max)}; T_j = 125^\circ\text{C};$ $I_{TM} = 50\text{ A}; V_R = 25\text{ V}; dI_{TM}/dt = 30\text{ A}/\mu\text{s};$ $dV_D/dt = 50\text{ V}/\mu\text{s}$	-	70	-	$\mu$ s

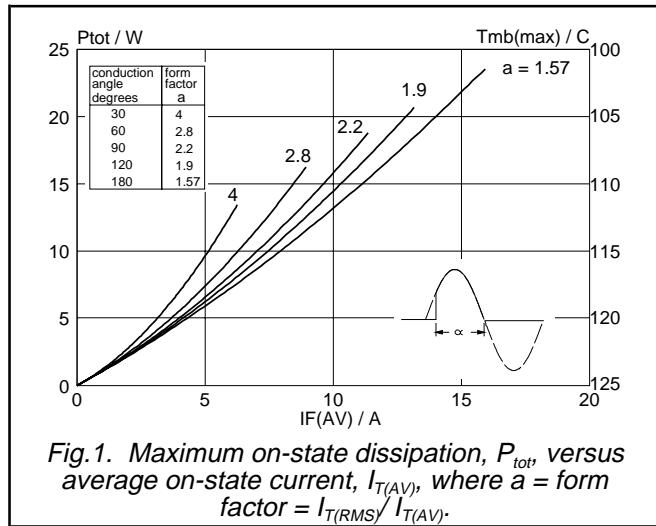


Fig.1. Maximum on-state dissipation,  $P_{tot}$ , versus average on-state current,  $I_{T(AV)}$ , where  $a$  = form factor =  $I_{T(RMS)} / I_{T(AV)}$ .

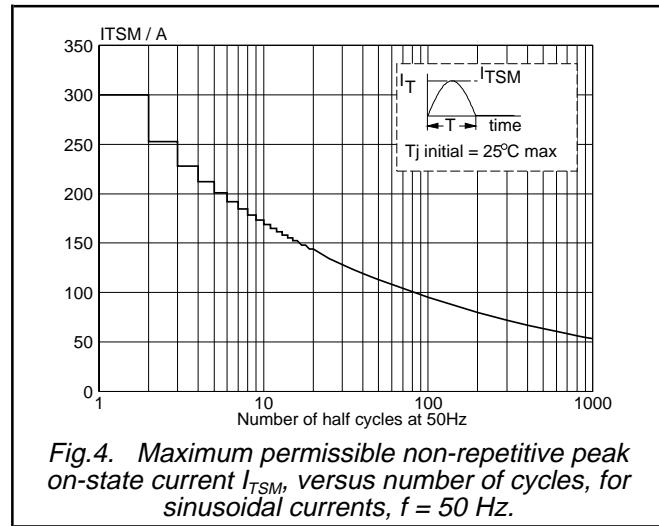


Fig.4. Maximum permissible non-repetitive peak on-state current  $I_{TSM}$ , versus number of cycles, for sinusoidal currents,  $f = 50$  Hz.

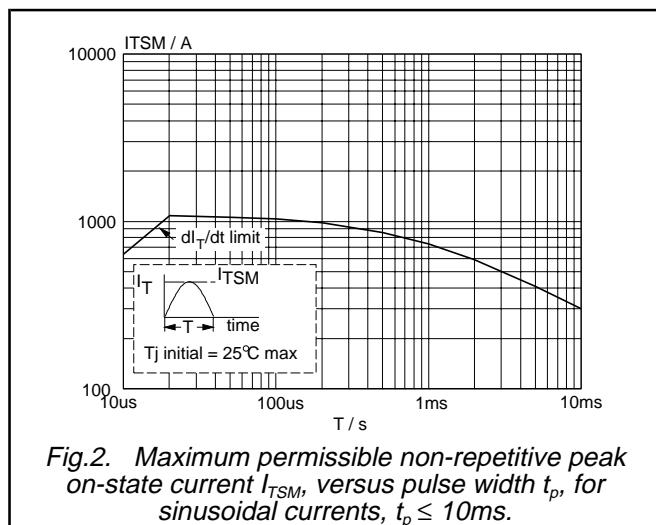


Fig.2. Maximum permissible non-repetitive peak on-state current  $I_{TSM}$ , versus pulse width  $t_p$ , for sinusoidal currents,  $t_p \leq 10$ ms.

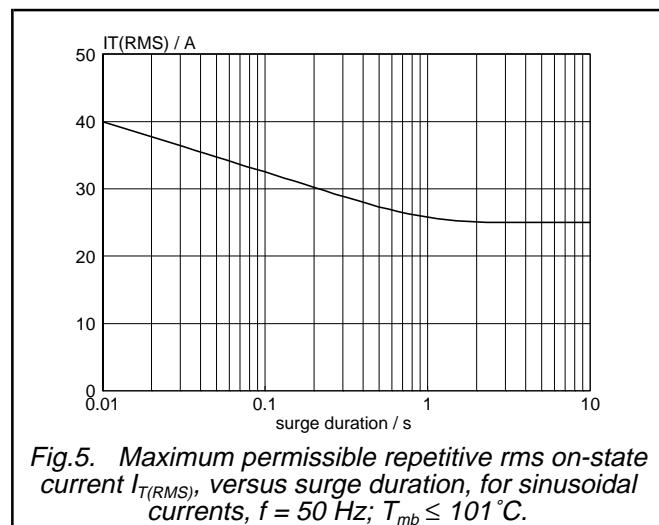


Fig.5. Maximum permissible repetitive rms on-state current  $I_{T(RMS)}$ , versus surge duration, for sinusoidal currents,  $f = 50$  Hz;  $T_{mb} \leq 101^\circ\text{C}$ .

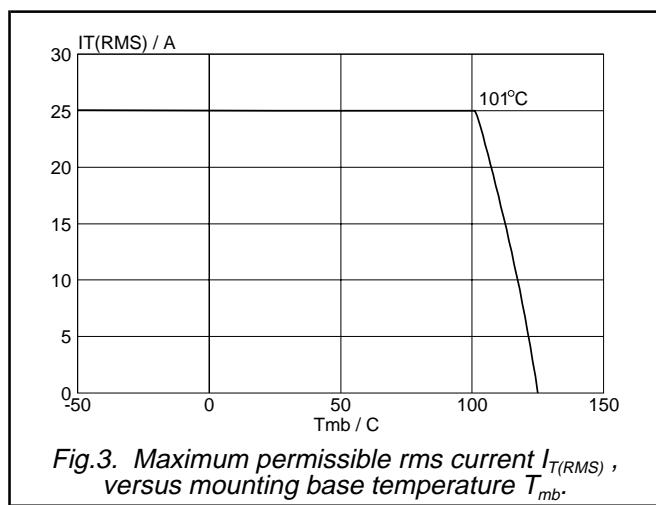


Fig.3. Maximum permissible rms current  $I_{T(RMS)}$ , versus mounting base temperature  $T_{mb}$ .

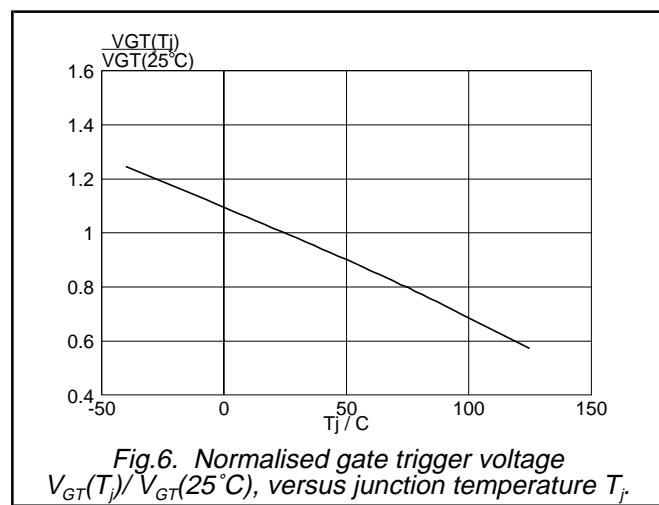
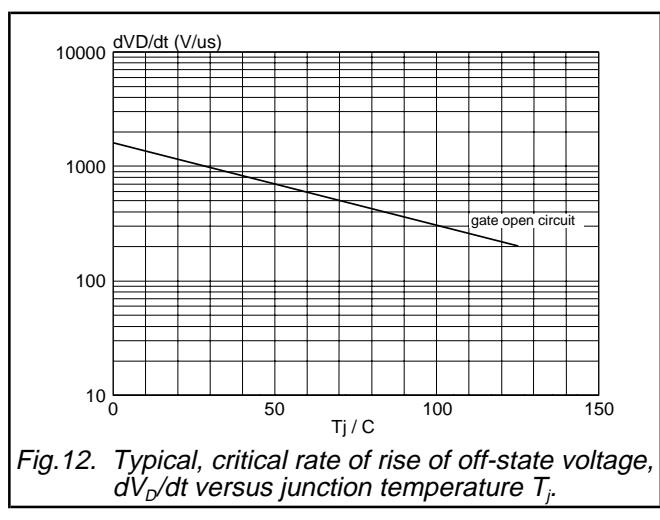
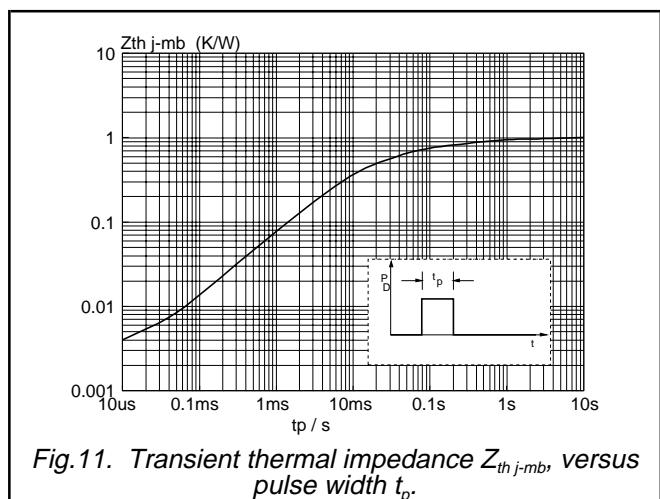
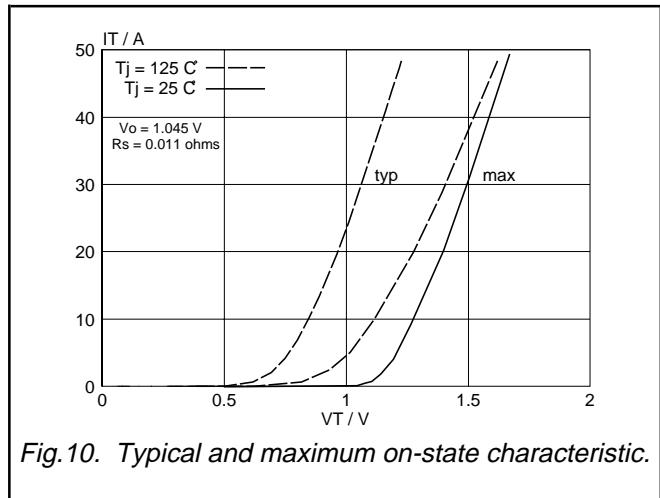
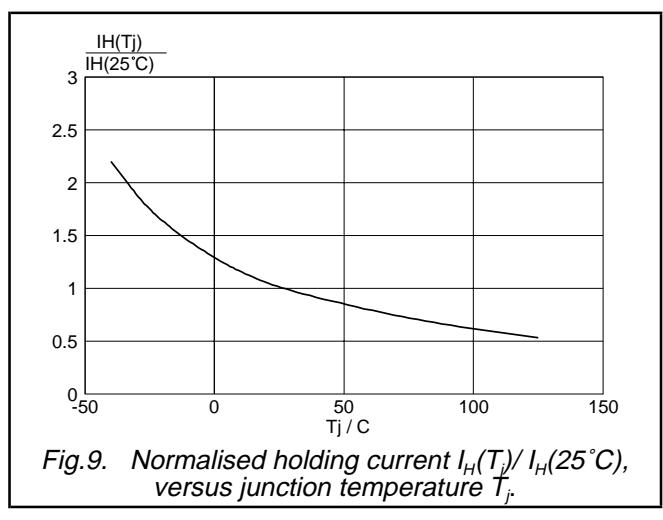
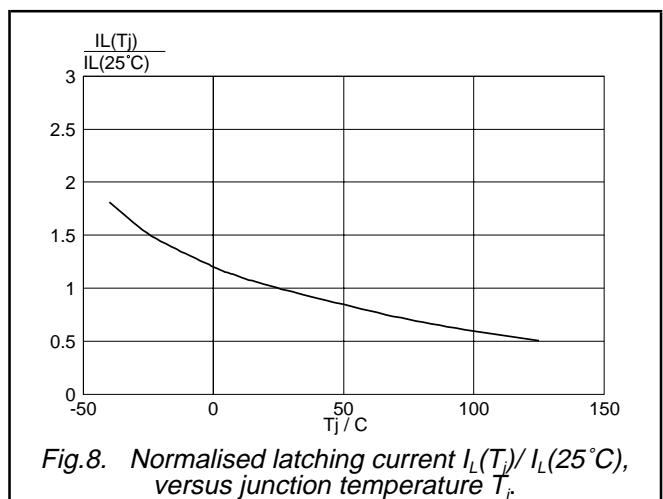
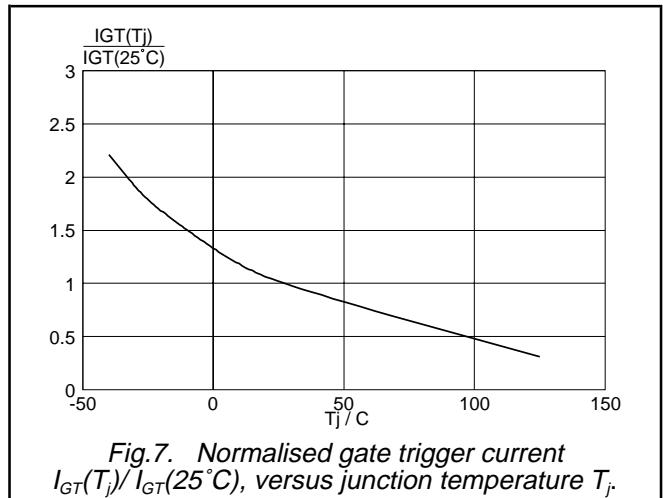


Fig.6. Normalised gate trigger voltage  $V_{GT}(T_j) / V_{GT}(25^\circ\text{C})$ , versus junction temperature  $T_j$ .



## MECHANICAL DATA

*Dimensions in mm*

Net Mass: 2 g

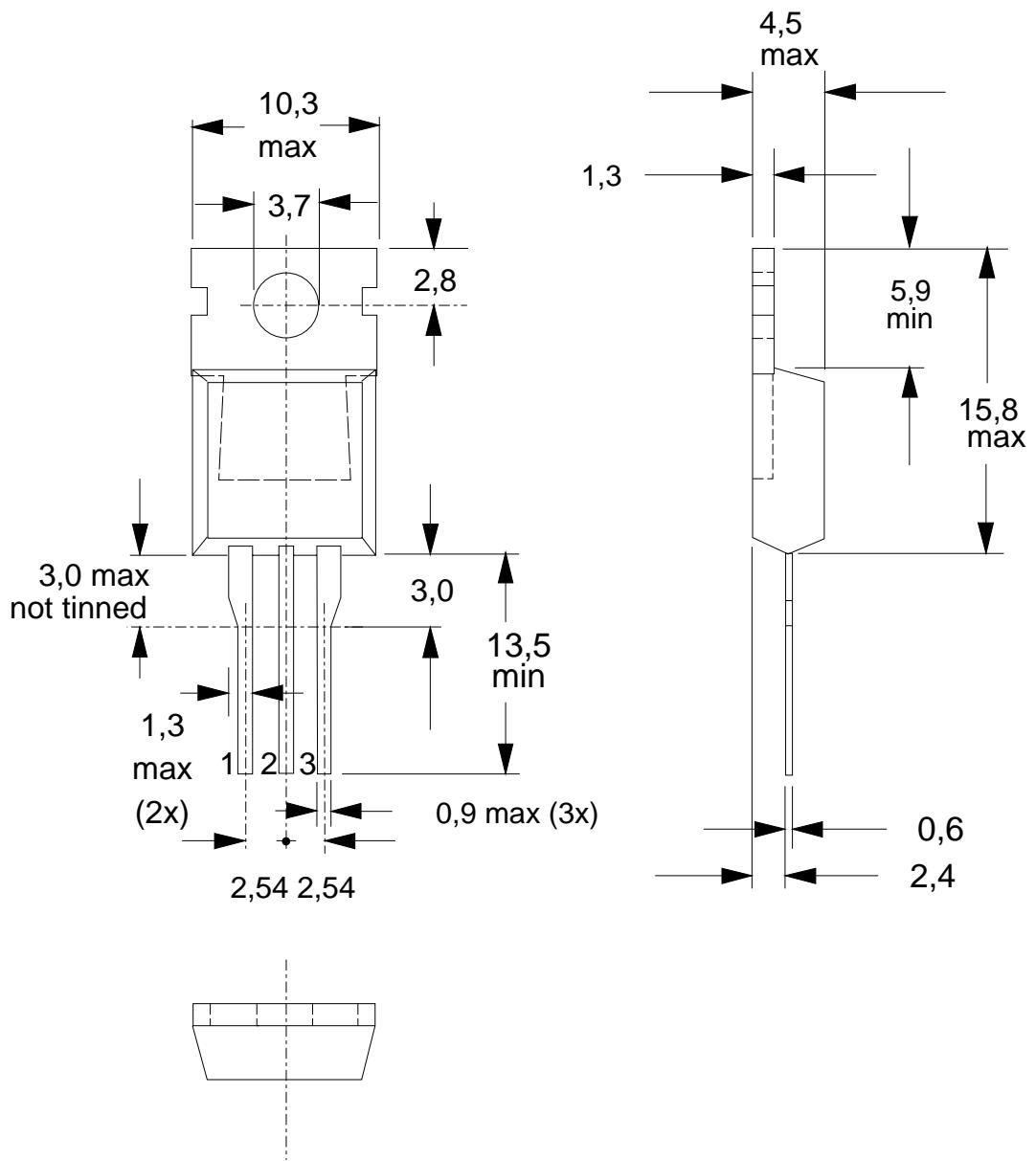


Fig.13. TO220AB; pin 2 connected to mounting base.

### Notes

1. Refer to mounting instructions for TO220 envelopes.
2. Epoxy meets UL94 V0 at 1/8".